WHAT IS CLAIMED IS:

1. A device comprising:

an integrated inductor; and

one or more electrically isolated metallic units disposed proximate to the inductor, the inductor and the one or more units to satisfy a metal density rule,

wherein substantially no current is to flow within one or more of the one or more metallic units during operation of the inductor.

2. A device according to Claim 1, wherein the inductor comprises a metal, and wherein one or more of the one or more metallic units comprises the metal.

3. A device according to Claim 2, wherein the metal is copper.

4. A device according to Claim 2, wherein the metal is aluminum.

5. A device according to Claim 1, wherein the inductor comprises a plurality of inductor elements disposed in respective ones of a plurality of device layers, and wherein the one or more metallic units are disposed proximate to the inductor elements in the plurality of device layers, the inductor elements and the one or more metallic units in a device layer to satisfy the metal density rule for the device layer.

6. A device according to Claim 1, wherein the inductor comprises a plurality of inductor elements, and wherein a width of one or more of the one or more metallic units is substantially smaller than a width of one or more of the plurality of inductor elements.

7. A device according to Claim 1, wherein the one or more metallic strips do not substantially decrease a Q of the inductor during operation of the inductor.

8. A method comprising:

fabricating an integrated inductor; and

fabricating one or more electrically isolated metallic units proximate to the inductor, the inductor and the one or more units to satisfy a metal density rule,

wherein substantially no current is to flow within one or more of the one or more metallic units during operation of the inductor.

9. A method according to Claim 8, wherein the inductor comprises a metal, and wherein one or more of the one or more metallic units comprises the metal.

10. A method according to Claim 9, wherein the metal is copper.

11. A method according to Claim 9, wherein the metal is aluminum.

12. A method according to Claim 8, wherein fabricating the inductor comprises:

fabricating a plurality of inductor elements in respective ones of a plurality of device layers, and

wherein fabricating the one or more metallic units comprises:

fabricating the one or more metallic units proximate to the inductor elements in the plurality of device layers,

the inductor elements and the one or more metallic units in a device layer to satisfy the metal density rule for the device layer.

13. A method according to Claim 8, wherein fabricating the inductor comprises:

fabricating a plurality of inductor elements, and

wherein fabricating the one or more metallic units comprises:

fabricating one or more of the one or more metallic units having a width substantially smaller than a width of one or more of the plurality of inductor elements.

14. A method according to Claim 8, wherein the one or more metallic strips do not substantially decrease a Q of the inductor during operation of the inductor.

15. A system comprising:

a controller comprising a voltage-controlled oscillator, the voltage-controlled oscillator comprising:

an integrated inductor; and

one or more electrically isolated metallic units disposed proximate to the inductor, the inductor and the one or more units to satisfy a metal density rule,

wherein substantially no current is to flow within one or more of the one or more metallic units during operation of the inductor; and

a double data rate memory in communication with the controller.

16. A system according to Claim 15, further comprising:

a processor coupled to the controller and to the memory, the processor to receive data from the controller and to transmit the data to the memory.